

**AEC-Q101 Qualified** 

# 2.5V Drive Nch MOSFET

# RJU003N03FRA

### Structure

Silicon N-channel MOSFET

# Features

- 1) Low On-resistance.
- 2) Low voltage drive (2.5V drive).

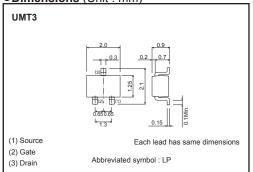
# Applications

Switching

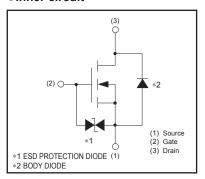
# ●Packaging specifications and hfe

	Package	Taping
Type	Code	T106
	Basic ordering unit (pieces)	3000
RJU003N03	0	

# ●Dimensions (Unit: mm)



### •Inner circuit



# ● Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit	
Drain-source voltage		VDSS	30	V
Gate-source voltage		V <sub>GSS</sub>	±12	V
Drain current	Continuous	I <sub>D</sub>	±300	mA
Drain current	Pulsed	I <sub>DP</sub> *1	±1.2	Α
Total power dissipation		P <sub>D</sub> *2	200	mW
Channel temperature		Tch	150	°C
Range of storage temperature	Tstg	-55 to +150	°C	

# Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	Rth(ch-a)*	625	°C/W

<sup>\*</sup> Each terminal mounted on a recommended land

<sup>\*1</sup> Pw≤10μs, Duty cycle≤1% \*2 Each terminal mounted on a recommended land

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# ●Electrical characteristics (Ta=25°C)

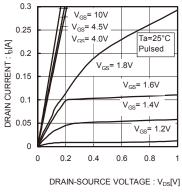
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Gate-source leakage	I <sub>GSS</sub>	_	_	±10	μΑ	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	
Drain-source breakdown voltage	$V_{(BR)DSS}$	30	_	_	V	I <sub>D</sub> = 1mA, V <sub>GS</sub> =0V	
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	1	μΑ	V <sub>DS</sub> = 30V, V <sub>GS</sub> =0V	
Gate threshold voltage	V <sub>GS (th)</sub>	0.8	_	1.5	V	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	
Otatio designatura		_	0.8	1.1	Ω	I <sub>D</sub> = 300mA, V <sub>G</sub> s= 4.5V	
Static drain-source on-state resistance	R <sub>DS (on)</sub> *	-	0.9	1.3	Ω	I <sub>D</sub> = 300mA, V <sub>GS</sub> = 4V	
resistance		_	1.4	1.9	Ω	I <sub>D</sub> = 300mA, V <sub>GS</sub> = 2.5V	
Forward transfer admittance	Y <sub>fs</sub> *	0.4	_	-	S	V <sub>DS</sub> = 10V, I <sub>D</sub> = 300mA	
Input capacitance	Ciss	_	24	_	pF	V <sub>DS</sub> = 10V	
Output capacitance	Coss	_	11	_	pF	V <sub>GS</sub> =0V	
Reverse transfer capacitance	Crss	_	5	_	pF	f=1MHz	
Turn-on delay time	t <sub>d (on)</sub> *	-	6	-	ns	V <sub>DD</sub> ≒ 15V	
Rise time	tr *	_	4	_	ns	ID= 150mA	
Turn-off delay time	t <sub>d (off)</sub> *	_	9	_	ns	V <sub>GS</sub> = 4V R <sub>L</sub> =100Ω	
Fall time	t <sub>f</sub> *	_	32	_	ns	R <sub>G</sub> =10Ω	

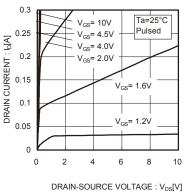
<sup>\*</sup>Pulsed

# ●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	VsD	_	_	1.2	V	I <sub>S</sub> = 200mA, V <sub>GS</sub> =0V

### •Electrical characteristics curves





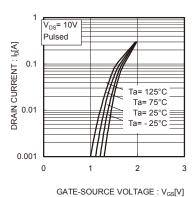
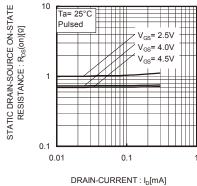
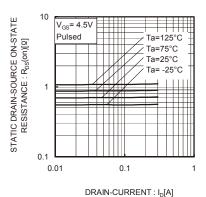


Fig.1 Typical Output Characteristics( I )

Fig.2 Typical Output Characteristics( II )

Fig.3 Typical Transfer Characteristics





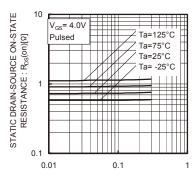
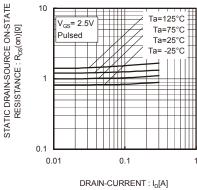
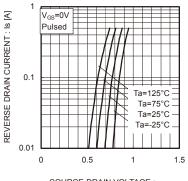


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( II )

 $\mathsf{DRAIN}\text{-}\mathsf{CURRENT}:\mathsf{I}_\mathsf{D}\![\mathsf{A}]$ Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(Ⅲ)





STATIC DRAIN-SOURCE ON-STATE RESISTANCE :  $R_{DS}(ON)[\Omega]$ 10 I<sub>D</sub>= 100mA 6 In= 300mA Ta=25°C 2 Pulsed 0 0 2 6 8 10

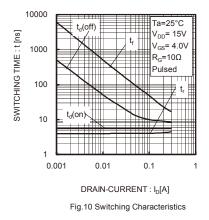
Fig.7 Static Drain-Source On-State Resistance vs. Drain Current(IV)

SOURCE-DRAIN VOLTAGE: Fig.8 Reverse Drain Current vs. Sourse-Drain Voltage

Fig.9 Static Drain-Source On-State Resistance vs. Gate Source Voltage

GATE-SOURCE VOLTAGE :  $V_{GS}[V]$ 

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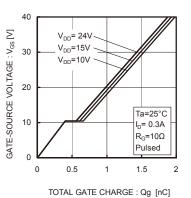
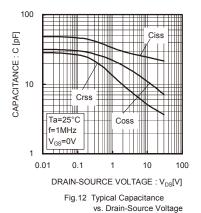
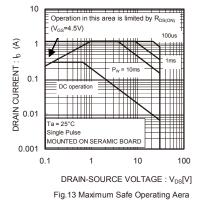


Fig.11 Dynamic Input Characteristics





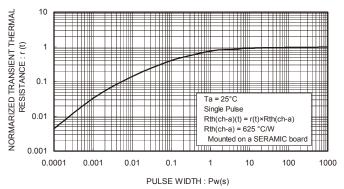


Fig.14 Normalized Transient Thermal Resistance vs. Pulse Width

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLACCIII	CLASS II b	ОГАССШ
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

# **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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QR code printed on ROHM Products label is for ROHM's internal use only.

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